SDAS085B - APRIL 1982 - REVISED DECEMBER 1994

Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

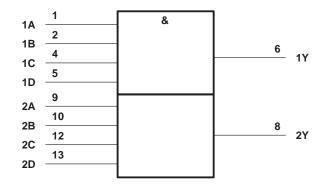
These devices contain two independent 4-input positive-AND gates. They perform the Boolean functions $Y = A \bullet B \bullet C \bullet D$ or $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$ in positive logic.

The SN54ALS21A and **SN54AS21** characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS21A and SN74AS21 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

	INP		OUTPUT	
Α	В	С	D	Υ
Н	Н	Н	Н	Н
L	Χ	Χ	X	L
Х	L	Χ	X	L
Х	Χ	L	X	L
Х	Χ	Χ	L	L

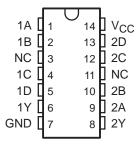
logic symbol†



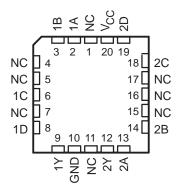
[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS21A, SN54AS21...J PACKAGE SN74ALS21A, SN74AS21...D OR N PACKAGE (TOP VIEW)

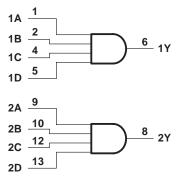


SN54ALS21A, SN54AS21 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram (positive logic)



SN54ALS21A, SN54AS21, SN74ALS21A, SN74AS21 DUAL 4-INPUT POSITIVE-AND GATES

SDAS085B - APRIL 1982 - REVISED DECEMBER 1994

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

recommended operating conditions

		SN54ALS21A			SN	1A		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
lOH	High-level output current			-0.4			-0.4	mA
lOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555		TEST CONDITIONS					74ALS2	1A	UNIT
PARAMETER	TEST CO	ONDITIONS	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNII
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2)		VCC -2	2		V
V/	\/	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 8 mA					0.35	0.5	V
lį	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
lН	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.4 V			-0.1			-0.1	mA
ΙΟ§	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-20		-112	-30		-112	mA
ICCH	V _{CC} = 5.5 V,	V _I = 4.5 V		0.85	1.4		0.85	1.4	mA
ICCL	V _{CC} = 5.5 V,	V _I = 0		1.4	2.3		1.4	2.3	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R _L T _A	UNIT			
			SN54AI	LS21A	SN74A	LS21A	
			MIN	MAX	MIN	MAX	
t _{PLH}	A, B, C, or D	V	4	18	4	15	
^t PHL	A, B, C, OI D	1	2	15	2	10	ns

 $[\]P$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SN54ALS21A, SN54AS21, SN74ALS21A, SN74AS21 DUAL 4-INPUT POSITIVE-AND GATES

SDAS085B - APRIL 1982 - REVISED DECEMBER 1994

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54AS21	55°C to 125°C
SN74AS21	0°C to 70°C
Storage temperature range	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS21			S	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-2			-2	mA
l _{OL}	Low-level output current			20			20	mA
T _A	Operating free-air temperature	-55	·	125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TTOT COURTING				S			
PARAMETER	TEST C	TEST CONDITIONS			MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
V _{OL}	V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.35	0.5		0.35	0.5	V
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
lн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.5			-0.5	mA
Ι _Ο §	$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-30		-112	-30		-112	mA
ICCH	$V_{CC} = 5.5 V,$	V _I = 4.5 V		2.9	4.6		2.9	4.6	mA
ICCL	V _{CC} = 5.5 V,	V _I = 0		7.4	12		7.4	12	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

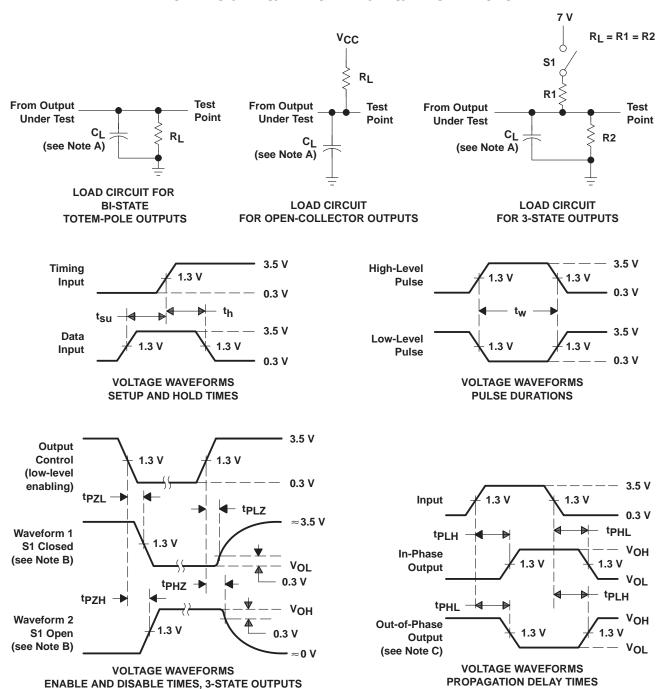
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R _L T _A	1 6.5 1 6			
^t PLH	A, B, C, or D	~	1	6.5	1	6	no
^t PHL	А, Б, С, 01 Б	T	1	6.5	1	6	ns

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
84143012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84143012A SNJ54ALS 21AFK	Sample
8414301CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8414301CA SNJ54ALS21AJ	Sample
SN54ALS21AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS21AJ	Sample
SN74ALS21AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS21A	Sample
SN74ALS21ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS21A	Sample
SN74ALS21ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS21A	Sample
SN74ALS21AN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS21AN	Sample
SN74ALS21ANSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS21A	Sample
SN74AS21D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS21	Sample
SN74AS21N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS21N	Sample
SN74AS21NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS21	Sample
SNJ54ALS21AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84143012A SNJ54ALS 21AFK	Sample
SNJ54ALS21AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8414301CA SNJ54ALS21AJ	Sample

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

PACKAGE OPTION ADDENDUM



24-Aug-2018

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS21A, SN74ALS21A:

Catalog: SN74ALS21A

Military: SN54ALS21A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 2-Sep-2015

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter		A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS21ADR	SOIC	D	14	2500	(mm) 330.0	W1 (mm) 16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS21ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS21NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 2-Sep-2015



*All dimensions are nominal

7 till diffrierene die Frentieren							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS21ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ALS21ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AS21NSR	SO	NS	14	2000	367.0	367.0	38.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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